

Title (en)
Lamp assembly heater and base

Title (de)
Heizvorrichtung und Sockel für eine Lampenanordnung

Title (fr)
Dispositif de chauffage et culot pour un agencement de lampe

Publication
EP 0872876 A1 19981021 (EN)

Application
EP 98107048 A 19980417

Priority
US 84450797 A 19970418

Abstract (en)
A lamp assembly is provided which includes a lamp (12) a lamp base (14) attached to the lamp (12), and a lamp heater. One or more abutment regions of the lamp (12) and the lamp base (14) mate with one another to provide axial and rotational orientation of the lamp (12) relative to the lamp base (14). The lamp heater conforms to the surface of the lamp (12) and may be bonded thereto by an adhesive. The lamp heater may include a heater element (16) and thermistor (18) adjacent to a surface of the lamp (12). The lamp (12), lamp heater and thermistor (18) are connected to a connector (22). A thermal breaker (20) is connected to the heater. The thermal breaker (20) provides a safety device to control maximum lamp temperature. The thermistor (18) controls the operating temperature of the lamp (12). The lamp assembly may include a display device (220) wherein the lamp (12) is secured to the display device (220). <IMAGE>

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H01J 61/52; H01J 5/54

IPC 8 full level
F21V 25/10 (2006.01); **H01J 5/54** (2006.01); **H01J 61/52** (2006.01)

CPC (source: EP)
H01J 5/54 (2013.01); **H01J 61/52** (2013.01)

Citation (search report)

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